

## 2 MHz, 2 A Synchronous Step-Down Converter

### General Description

The XTP8012 is a high-efficiency monolithic synchronous buck regulator using a constant frequency, current mode architecture. The device is available in an adjustable version. Supply current with no load is 70 $\mu$ A and drops to <1 $\mu$ A in shutdown. The 2.5V to 5.5V input voltage range makes the XTP8012 ideally suited for single Li-Ion battery powered applications. 100% duty cycle provides low dropout operation, extending battery life in portable systems. PWM/PFM mode operation provides very low output ripple voltage for noise sensitive applications.

Switching frequency is internally set at 2MHz, allowing the use of small surface mount inductors and capacitors. Low output voltages are easily supported with the 0.6V feedback reference voltage.

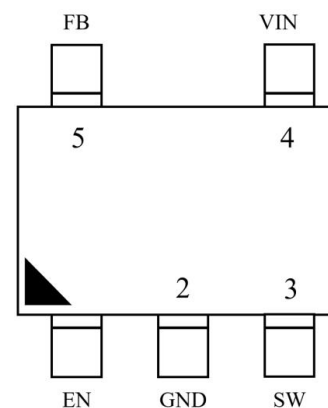
### Application

- Cellular and Smart Phones
- Wireless and DSL Modems
- Portable Instruments
- Digital Still and Video Cameras
- PC Card

### Features

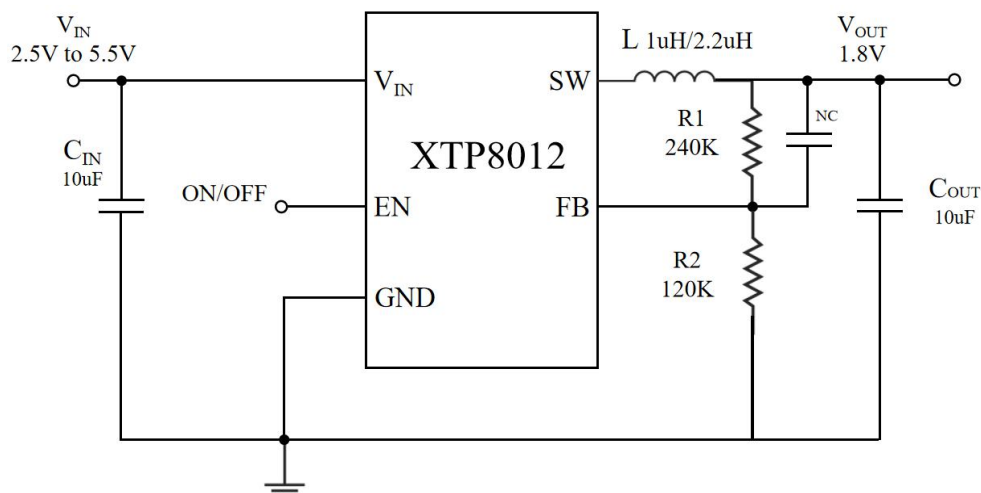
- High Efficiency: Up to 96%
- 2.5V to 5.5V Input Voltage Range
- 2MHz Constant Frequency Operation
- Low Dropout Operation: 100% Duty Cycle
- PFM Mode for High Efficiency in Light Load
- Over temperature Protected
- Low Quiescent Current: 70 $\mu$ A
- Short Circuit Protection
- Over Voltage Protection
- Inrush Current Limit and Soft Start
- RoHS and Halogen free compliance
- SOT23-5L package

### Typical Application Circuit



(SOT23-5)

## Typical Application Circuit



## Function Order Information

PIN	Pin Name	Pin Function
1	EN	Chip Enable Pin. Drive EN above 1V to turn on the part. Drive EN below 0.3V to turn it off. Do not leave EN floating.
2	GND	Ground Pin
3	SW	Power Switch Output. It is the switch node connection to Inductor. This pin connects to the drains of the internal P-ch and N-ch MOSFET switches.
4	V <sub>IN</sub>	Power Supply Input. Must be closely decoupled to GND with a 10 $\mu$ F or greater ceramic capacitor.
5	FB	Output Voltage Feedback Pin. An internal resistive divider divides the output voltage down for comparison to the internal reference voltage.

## Order Information

Part Number	Package	Top Marking	Quantity/Reel
XTP8012AS2CT	SOT23-5	P8012 YWZZX	3000

## MARKING INFORMATION

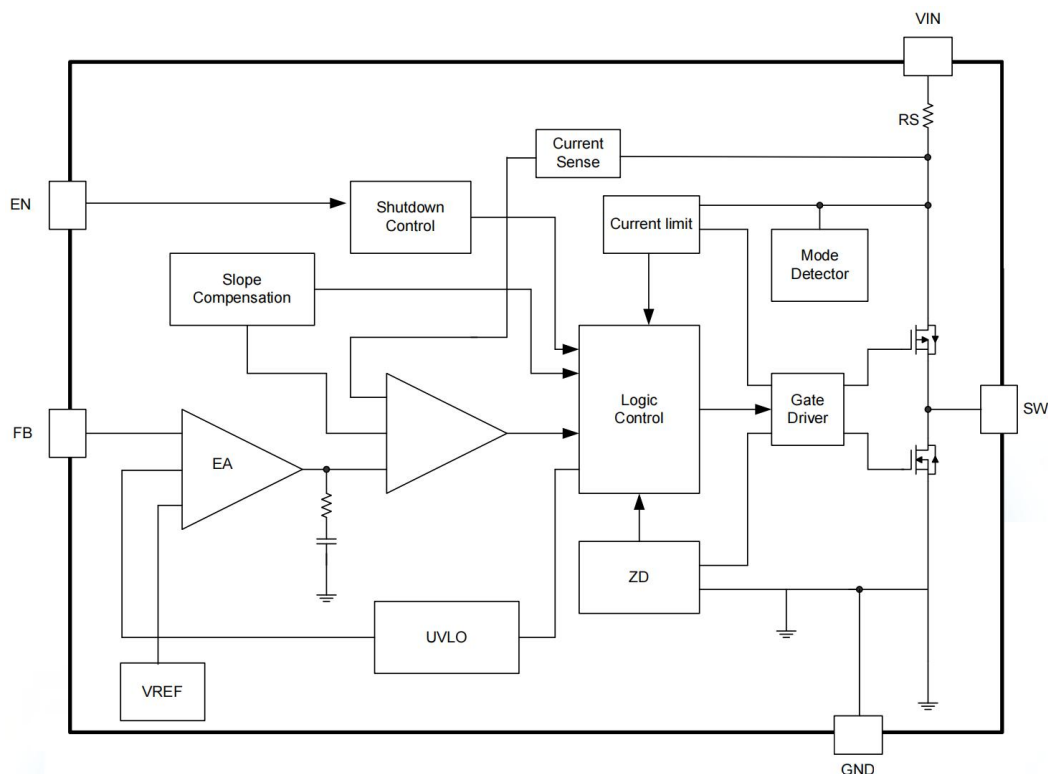
NOTE:

P8012: Device Code.

YW : Date Code.

ZZX: Inside Code.

## Function Block Diagram



## Absolute Maximum Ratings

PARAMETER		Min	Typ	Max	Unit
$V_{IN}$ to GND <sup>(1)</sup>		-0.3		7.0	V
EN Voltage		-0.3		6	V
SW Voltage		-0.3		$V_{in}+0.3$	V
Peak SW Sink and Source Current			2.2		A
Continuous Power Dissipation ( $T_A = 25^\circ\text{C}$ ) <sup>(2)</sup>	SOT23-5L		0.5		W
Junction Temperature		-40		165	$^\circ\text{C}$
Lead Temperature			260		$^\circ\text{C}$
Storage Temperature		-65		150	$^\circ\text{C}$
Thermal Resistance <sup>(3)</sup>	$\theta_{JA}$	SOT23-5L		170	$^\circ\text{C}/\text{W}$
	$\theta_{JC}$			75	

Notes:

- (1) Exceeding these ratings may damage the device.
- (2) The maximum allowable power dissipation is a function of the maximum junction temperature  $T_{J(MAX)}$ , the junction-to-ambient thermal resistance  $\theta_{JA}$ , and the ambient temperature  $T_A$ . The maximum allowable continuous power dissipation at any ambient temperature is calculated by  $PD(MAX) = (T_{J(MAX)} - T_A) / \theta_{JA}$ . Exceeding the maximum allowable power dissipation will cause excessive die temperature, and the regulator will go into thermal shutdown. Internal thermal shutdown circuitry protects the device from permanent damage.
- (3) Measured on JESD51-7, 4-layer PCB.

**Electrical Characteristics**

 All typical values are at T<sub>j</sub>=25°C (unless otherwise noted)

Parameter	Test Conditions	Min	Typ	Max	Unit
Input Voltage range		2.5	--	5.5	V
V <sub>OVP</sub>			6.1		V
UVLO		2.1	2.3	2.5	V
UVLO hysteresis		0.1	0.2	0.3	V
FB voltage	No load	588	600	612	mV
Switching frequency	V <sub>FB</sub> =0.5V	1.6	2	2.4	M
Max duty cycle			100		%
No load supply current a V <sub>IN</sub>			70	120	uA
Shutdown Supply Current at V <sub>IN</sub>	EN=0		0.1	1	uA
Efficiency	I <sub>LOAD</sub> =0.6A	85	90		%
Line regulation	I <sub>LOAD</sub> =300mA		0.1	0.2	%/V
Load regulation	I <sub>LOAD</sub> =0-1.0A		0.1	0.2	%/V
NMOS Switch On Resistance	I <sub>SW</sub> =100mA		80	160	mΩ
PMOS Switch On Resistance	I <sub>SW</sub> =100mA		160	320	mΩ
Peak Current Limit			3		A
SW Leakage Current	V <sub>IN</sub> = 6V, V <sub>SW</sub> = 0 or 6V, EN=0			10	uA
OTP		135	150	165	°C
OTP hysteresis		20	30	40	°C
EN Input Low Voltage				0.3	V
EN Input High Voltage		1			V

## Function Descriptions

The XTP8012 uses a constant frequency, current mode step-down architecture. Both the main (P-channel MOSFET) and synchronous (N-channel MOSFET) switches are internal. During normal operation, the internal top power MOSFET is turned on each cycle when the oscillator sets the RS latch, and turned off when the current comparator, ICOMP, resets the RS latch. The peak inductor current at which ICOMP resets the RS latch, is controlled by the output of error amplifier EA. When the load current increases, it causes a slight decrease in the feedback voltage, FB, relative to the 0.6V reference, which in turn, causes the EA amplifier's output voltage to increase until the average inductor current matches the new load current. While the top MOSFET is off, the bottom MOSFET is turned on until either the inductor current starts to reverse, as indicated by the current reversal comparator IRCMP, or the beginning of the next clock cycle.

## Setting the Output Voltage

In the adjustable version, the output voltage is set by a resistive divider according to the following formula:

$$R_2 = \frac{R_1}{\frac{V_{out}}{V_{FB}} - 1}$$

The external resistive divider is connected to the output, allowing remote voltage sensing as shown in on page 1.

## Inductor Selection

For most designs, the XTP8012 operates with inductors of 1μH to 4.7μH. Low inductance values are physically smaller but require faster switching, which results in some efficiency loss. The inductor value can be derived from the following equation:

$$L = \frac{V_{OUT} \times (V_{IN} - V_{OUT})}{V_{IN} \times \Delta I_L \times f_{OSC}}$$

Where  $\Delta I_L$  is inductor Ripple Current. Large value inductors result in lower ripple current and small value inductors result in high ripple current. For optimum voltage-positioning load transients, choose an inductor with DC series resistance in the 50mΩ to 150mΩ range.

## Input Capacitor Selection

Higher values, lower cost ceramic capacitors are now becoming available in smaller case sizes. Their high ripple current, high voltage rating and low ESR make them ideal for switching regulator applications. Because the XTP8012's control loop does not depend on the output capacitor's ESR for stable operation, ceramic capacitors can be used freely to achieve very low output ripple and small circuit size. However, care must be taken when ceramic capacitors are used at the input and the output. When a ceramic capacitor is used at the input and the power is supplied by a wall adapter through long wires, a load step at the output can induce ringing at the input,  $V_{IN}$ . At best, this ringing can couple to the output and be mistaken as loop instability. At worst, a sudden inrush of current through the long wires can potentially cause a voltage spike at  $V_{IN}$ , large enough to damage the part. When choosing the input and output ceramic capacitors, choose the X5R or X7R dielectric formulations. These dielectrics have the best temperature and voltage characteristics of all the ceramics for a given value and size.

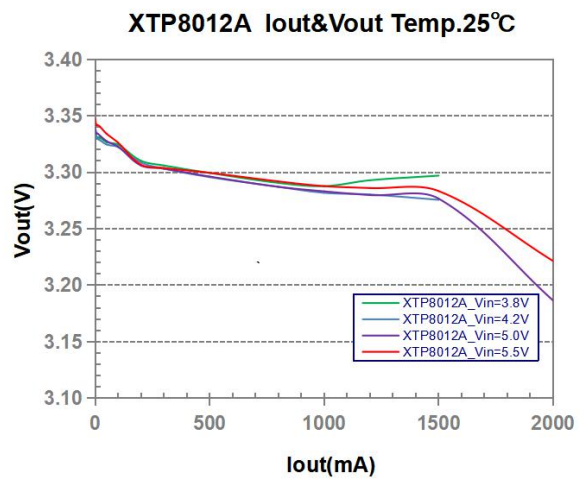
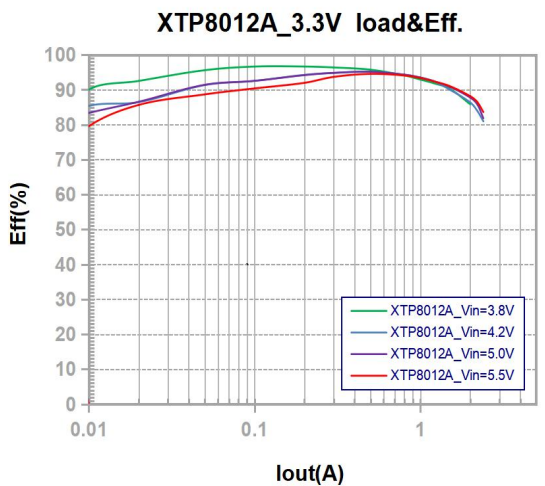
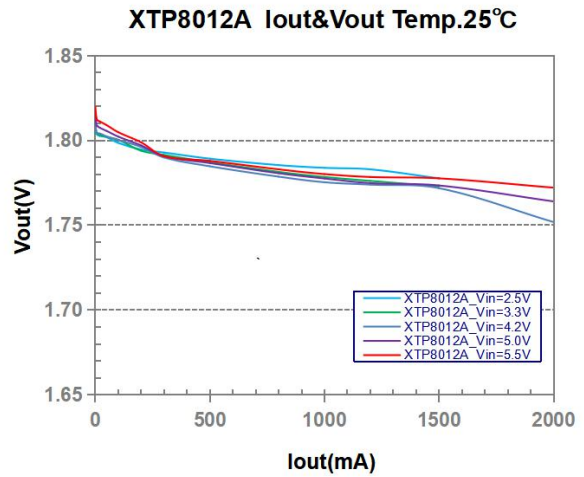
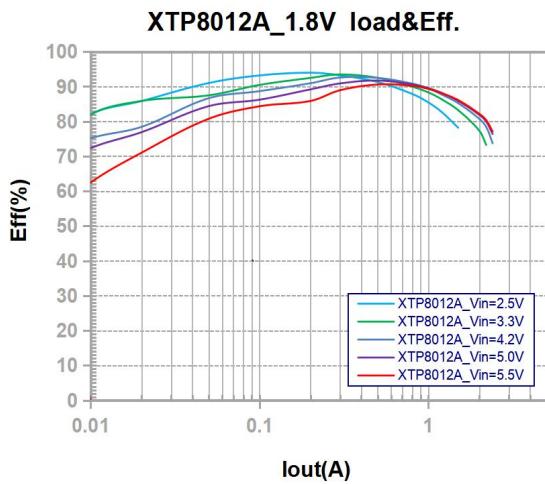
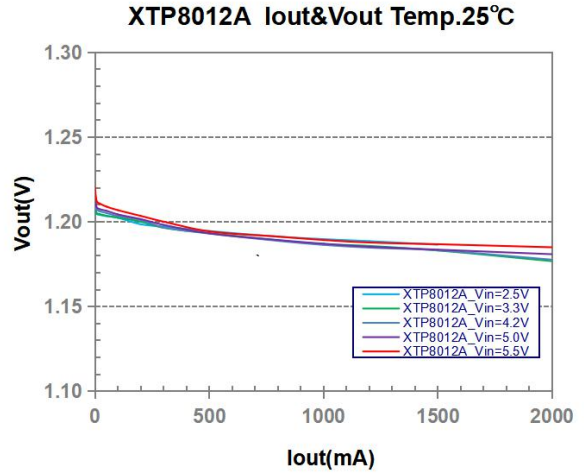
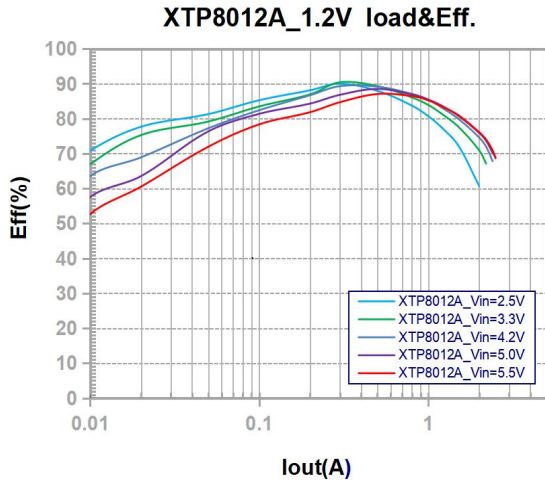
## PCB Layout Checklist

When laying out the printed circuit board, the following checking should be used to ensure proper operation of the XTP8012. Check the following in your layout:

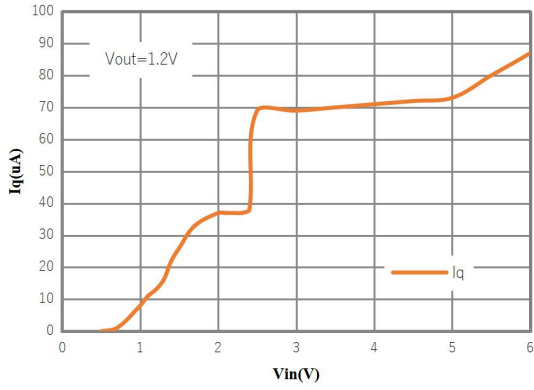
1. The power traces, consisting of the GND trace, the SW trace and the  $V_{IN}$  trace should be kept short, direct and wide.
2. Place the  $C_{IN}$  to XTP8012's  $V_{IN}$  and GND pins as closely as possible. This capacitor provides the AC current to the internal power MOSFETs.
3. Better to make a star connection of ground node for  $C_{IN}$ , XTP8012's ground and  $C_{OUT}$ .
4. Keep the switching node, SW, away from the sensitive feedback node.
5. Keep the (-) terminal of  $C_{IN}$  and  $C_{OUT}$  as close as possible, to minimize current loop area for EMI concern.

## Typical Characteristics

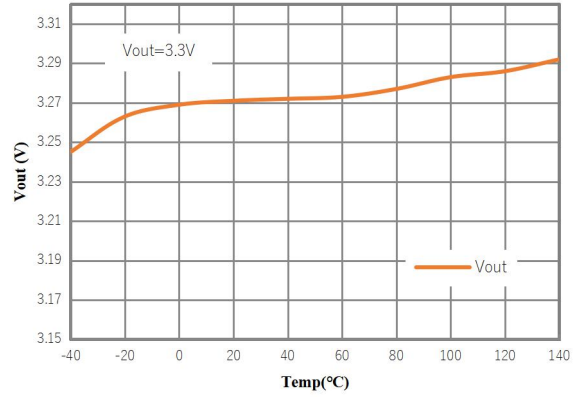
( $C_{IN}=C_{OUT}=10\mu F$ ,  $L=2.2\mu H$ ,  $14m\Omega$ ,  $T_A = 25^\circ C$ , unless otherwise specified)



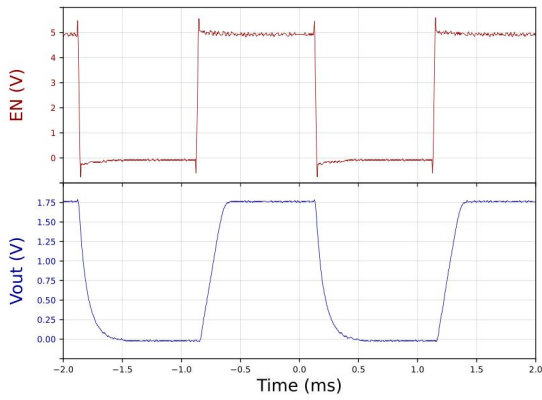
**Iq VS. Vin**



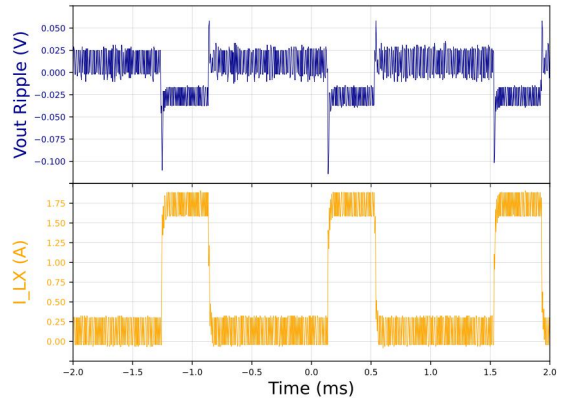
**Vout VS Temp**



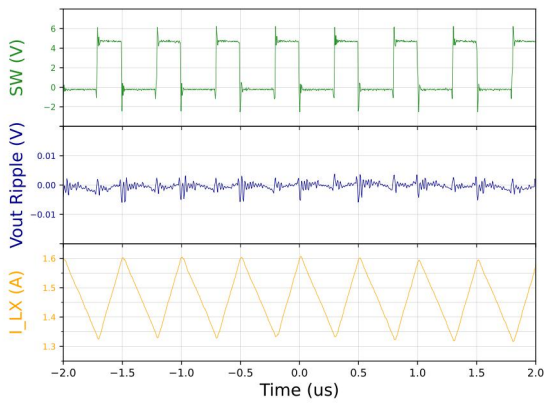
**EN ON\_OFF, Vin=5V, Vout=1.8V, Iout=0.5A**



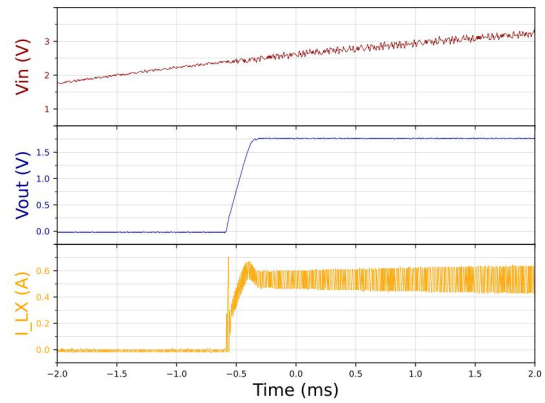
**Load Transient Vin=5V, Vout=1.8V, Iout=0.1\_1.8A**



**Operation Waveform Vin=5V, Vout=1.8V, Iout=1.5A**



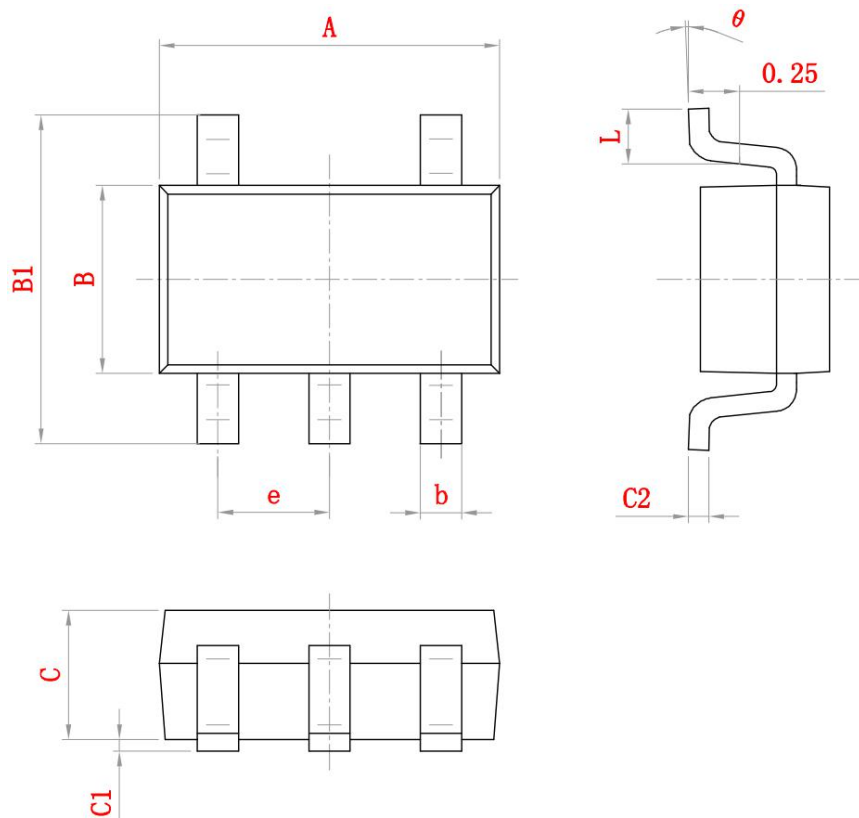
**Power ON, Vin=5V, Vout=1.8V, Iout=0.5A**





## Package Information

Package dimension (mm)



SOT23-5L

Symbol	Min(mm)	Max(mm)	Symbol	Min(mm)	Max(mm)
A	2.82	3.02	C	1.05	1.15
e	0.95(BSC)		C1	0.03	0.15
b	0.28	0.45	C2	0.12	0.23
B	1.50	1.70	L	0.35	0.55
B1	2.60	3.00	$\theta$	0°	8°